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SH7670 Group

User's Manual: Hardware

Renesas 32-Bit RISC Microcomputer
SuperH™ RISC engine Family / SH7670 Series

SH7670	R5S76700
SH7671	R5S76710
SH7672	R5S76720
SH7673	R5S76730

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General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different type number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different type numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different type numbers, implement a system-evaluation test for each of the products.

How to Use This Manual

1. Objective and Target Users

This manual was written to explain the hardware functions and electrical characteristics of this LSI to the target users, i.e. those who will be using this LSI in the design of application systems. Target users are expected to understand the fundamentals of electrical circuits, logic circuits, and microcomputers.

This manual is organized in the following items: an overview of the product, descriptions of the CPU, system control functions, and peripheral functions, electrical characteristics of the device, and usage notes.

When designing an application system that includes this LSI, take all points to note into account. Points to note are given in their contexts and at the final part of each section, and in the section giving usage notes.

The list of revisions is a summary of major points of revision or addition for earlier versions. It does not cover all revised items. For details on the revised points, see the actual locations in the manual.

The following documents have been prepared for the SH7670 Group. Before using any of the documents, please visit our web site to verify that you have the most up-to-date available version of the document.

Document Type	Contents	Document Title	Document No.
Data Sheet	Overview of hardware and electrical characteristics	—	—
User's manual for Hardware	Hardware specifications (pin assignments, memory maps, peripheral specifications, electrical characteristics, and timing charts) and descriptions of operation	SH7670 Group User's Manual: Hardware	This User's manual
User's manual for Software	Detailed descriptions of the CPU and instruction set	SH-2A, SH2A-FPU Software Manual	REJ09B0051
Application Note	Examples of applications and sample programs	The latest versions are available from our web site.	
Renesas Technical Update	Preliminary report on the specifications of a product, document, etc.		

2. Description of Numbers and Symbols

Aspects of the notations for register names, bit names, numbers, and symbolic names in this manual are explained below.

(1) Overall notation

In descriptions involving the names of bits and bit fields within this manual, the modules and registers to which the bits belong may be clarified by giving the names in the forms "module name"."register name"."bit name" or "register name"."bit name".

(2) Register notation

The style "register name"_"instance number" is used in cases where there is more than one instance of the same function or similar functions.

[Example] CMCSR_0: Indicates the CMCSR register for the compare-match timer of channel 0.

(3) Number notation

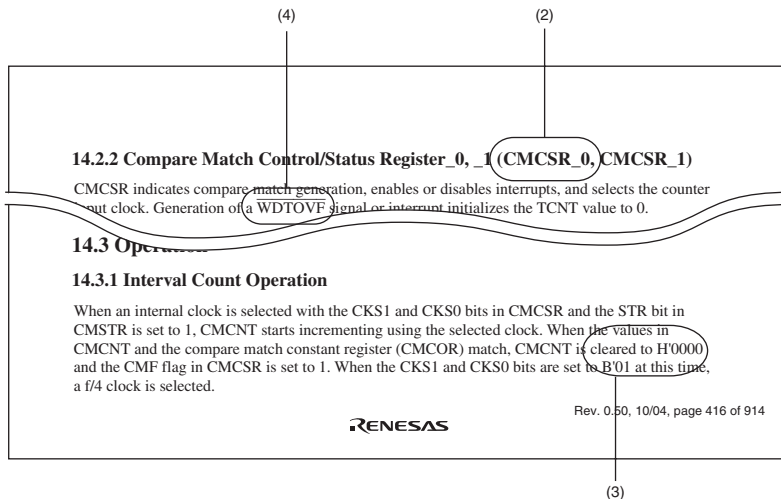
Binary numbers are given as B'nnnn (B' may be omitted if the number is obviously binary), hexadecimal numbers are given as H'nnnn or 0xnnnn, and decimal numbers are given as nnnn.

[Examples] Binary: B'11 or 11
Hexadecimal: H'EFA0 or 0xEFA0
Decimal: 1234

(4) Notation for active-low

An overbar on the name indicates that a signal or pin is active-low.

[Example] WDTOVF



Note: The bit names and sentences in the above figure are examples and have nothing to do with the contents of this manual.

3. Description of Registers

Each register description includes a bit chart, illustrating the arrangement of bits, and a table of bits, describing the meanings of the bit settings. The standard format and notation for bit charts and tables are described below.

[Bit Chart]

Bit:	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	—	—	ASID2	ASID1	ASID0	—	—	—	—	—	—	Q	ACMP2	ACMP1	ACMP0	IFE
Initial value:	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[Table of Bits]

Bit	Bit Name	Initial Value	R/W	Description
15 14	—	0	R	Reserved These bits are always read as 0.
13 to 11	ASID2 to ASID0	All 0	R/W	Address Identifier These bits enable or disable the pin function.
10	—	0	R	Reserved This bit is always read as 0.
9	—	1	R	Reserved This bit is always read as 1.
—	—	0	—	—

Note: The bit names and sentences in the above figure are examples, and have nothing to do with the contents of this manual.

- (1) Bit
Indicates the bit number or numbers.
In the case of a 32-bit register, the bits are arranged in order from 31 to 0. In the case of a 16-bit register, the bits are arranged in order from 15 to 0.
- (2) Bit name
Indicates the name of the bit or bit field.
When the number of bits has to be clearly indicated in the field, appropriate notation is included (e.g., ASID[3:0]).
A reserved bit is indicated by "—".
Certain kinds of bits, such as those of timer counters, are not assigned bit names. In such cases, the entry under Bit Name is blank.
- (3) Initial value
Indicates the value of each bit immediately after a power-on reset, i.e., the initial value.
0: The initial value is 0
1: The initial value is 1
—: The initial value is undefined
- (4) R/W
For each bit and bit field, this entry indicates whether the bit or field is readable or writable, or both writing to and reading from the bit or field are impossible.
The notation is as follows:
R/W: The bit or field is readable and writable.
R/(W): The bit or field is readable and writable.
However, writing is only performed to flag clearing.
R: The bit or field is readable.
"R" is indicated for all reserved bits. When writing to the register, write the value under Initial Value in the bit chart to reserved bits or fields.
W: The bit or field is writable.
- (5) Description
Describes the function of the bit or field and specifies the values for writing.

4. Description of Abbreviations

The abbreviations used in this manual are listed below.

- Abbreviations specific to this product

Abbreviation	Description
BSC	Bus controller
CPG	Clock pulse generator
DTC	Data transfer controller
INTC	Interrupt controller

- Abbreviations other than those listed above

Abbreviation	Description
ACIA	Asynchronous communications interface adapter
bps	Bits per second
CRC	Cyclic redundancy check
DMA	Direct memory access
DMAC	Direct memory access controller
GSM	Global System for Mobile Communications
Hi-Z	High impedance
I/O	Input/output
IrDA	Infrared Data Association
LSB	Least significant bit
MSB	Most significant bit
NC	No connection
PLL	Phase-locked loop
PWM	Pulse width modulation
SFR	Special function register
SIM	Subscriber Identity Module
UART	Universal asynchronous receiver/transmitter
VCO	Voltage-controlled oscillator

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